

ZXTD2M832

MPPS™ Miniature Package Power Solutions DUAL 20V PNP LOW SATURATION SWITCHING TRANSISTOR

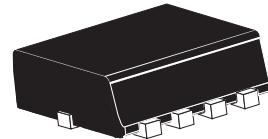
SUMMARY

$V_{CEO} = -20V$; $R_{SAT} = 64m\Omega$; $I_C = -3.5A$

DESCRIPTION

Packaged in the innovative 3mm x 2mm MLP (Micro Leaded Package) outline, these new 4th generation low saturation dual transistors offer extremely low on state losses making them ideal for use in DC-DC circuits and various driving and power management functions.

Additionally users gain several other **key benefits**:



Performance capability equivalent to much larger packages

Improved circuit efficiency & power levels

3mm x 2mm (Dual die) MLP

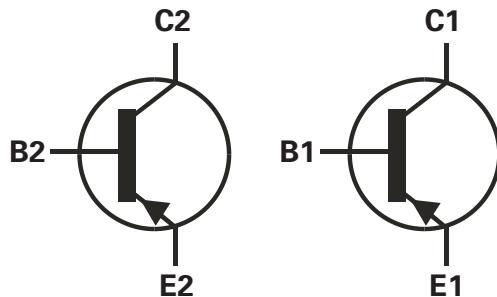
PCB area and device placement savings

Lower package height (nom 0.9mm)

Reduced component count

FEATURES

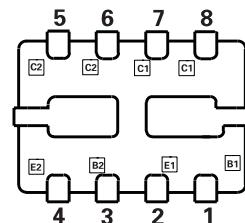
- Low Equivalent On Resistance
- Extremely Low Saturation Voltage (-220mV @ -1A)
- h_{FE} characterised up to -6A
- $I_C = -3.5A$ Continuous Collector Current
- 3mm x 2mm MLP



APPLICATIONS

- DC - DC Converters (FET Drivers)
- Charging circuits
- Power switches
- Motor control
- LED Backlighting circuits

PINOUT



3mm x 2mm MLP
underside view

ORDERING INFORMATION

DEVICE	REEL	TAPE WIDTH	QUANTITY PER REEL
ZXTD2M832TA	7"	8mm	3000
ZXTD2M832TC	13"	8mm	10000

DEVICE MARKING

D22

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ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Collector-Base Voltage	V_{CBO}	-25	V
Collector-Emitter Voltage	V_{CEO}	-20	V
Emitter-Base Voltage	V_{EBO}	-7.5	V
Peak Pulse Current	I_{CM}	-6	A
Continuous Collector Current (a)(f)	I_C	-3.5	A
Base Current	I_B	-1000	mA
Power Dissipation at TA=25°C (a)(f) Linear Derating Factor	P_D	1.5 12	W mW/°C
Power Dissipation at TA=25°C (b)(f) Linear Derating Factor	P_D	2.45 19.6	W mW/°C
Power Dissipation at TA=25°C (c)(f) Linear Derating Factor	P_D	1 8	W mW/°C
Power Dissipation at TA=25°C (d)(f) Linear Derating Factor	P_D	1.13 9	W mW/°C
Power Dissipation at TA=25°C (d)(g) Linear Derating Factor	P_D	1.7 13.6	W mW/°C
Power Dissipation at TA=25°C (e)(g) Linear Derating Factor	P_D	3 24	W mW/°C
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(f)	$R_{\theta JA}$	83.3	°C/W
Junction to Ambient (b)(f)	$R_{\theta JA}$	51	°C/W
Junction to Ambient (c)(f)	$R_{\theta JA}$	125	°C/W
Junction to Ambient (d)(f)	$R_{\theta JA}$	111	°C/W
Junction to Ambient (d)(g)	$R_{\theta JA}$	73.5	°C/W
Junction to Ambient (e)(g)	$R_{\theta JA}$	41.7	°C/W

Notes

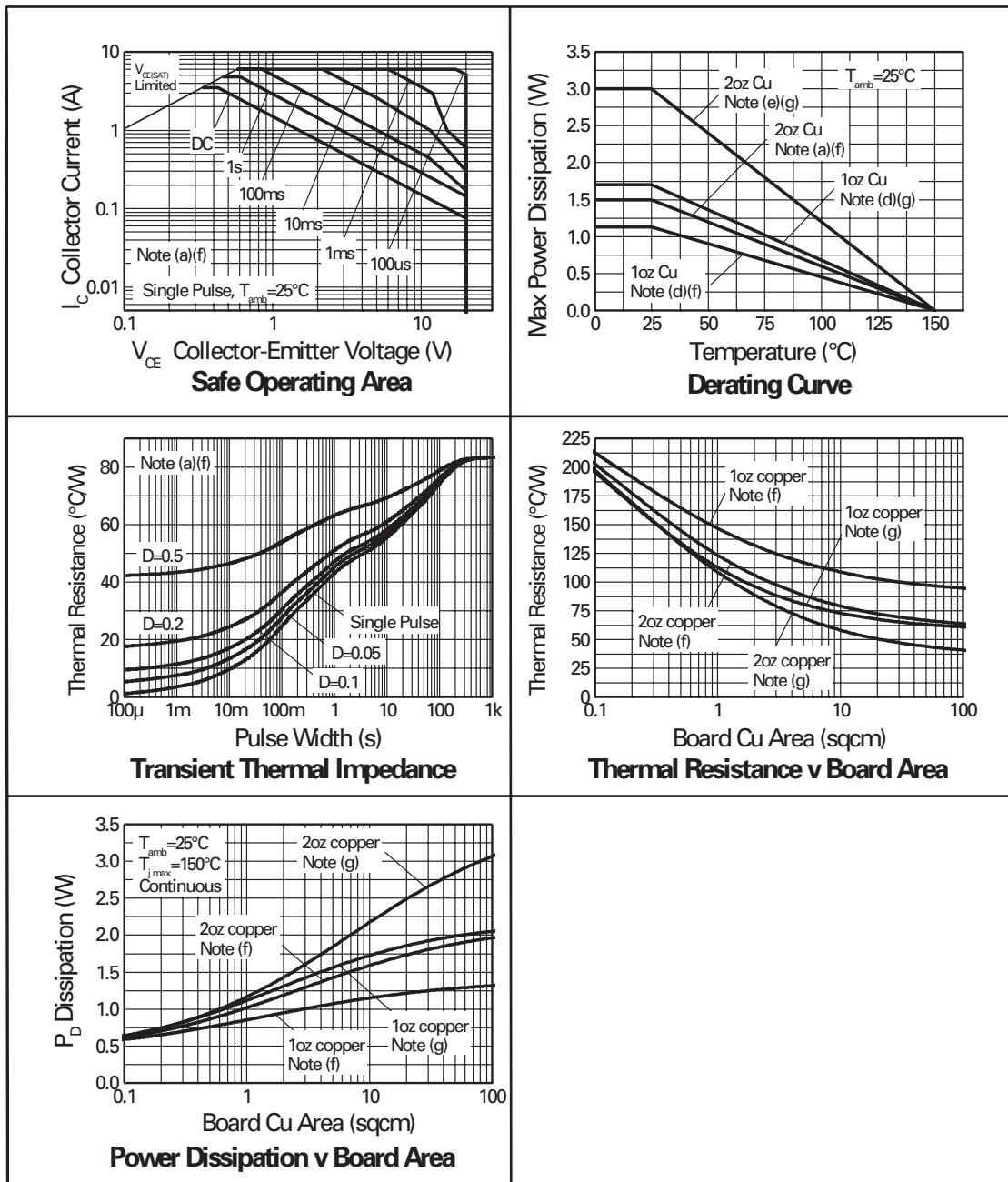
- (a) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (b) Measured at t<5 secs for a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (c) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with minimal lead connections only**.
- (d) For a dual device surface mounted on 10 sq cm single sided 1oz copper on FR4 PCB, in still air conditions **with all exposed pads attached attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (e) For a dual device surface mounted on 85 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (f) For a dual device with one active die.
- (g) For dual device with 2 active die running at equal power.
- (h) Repetitive rating - pulse width limited by max junction temperature. Refer to Transient Thermal Impedance graph.
- (i) The minimum copper dimensions required for mounting are no smaller than the exposed metal pads on the base of the device as shown in the package dimensions data. The thermal resistance for a dual device mounted on 1.5mm thick FR4 board using minimum copper 1 oz weight, 1mm wide tracks and one half of the device active is $R_{th} = 250^{\circ}\text{C}/\text{W}$ giving a power rating of $P_{tot} = 500\text{mW}$.



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TYPICAL CHARACTERISTICS



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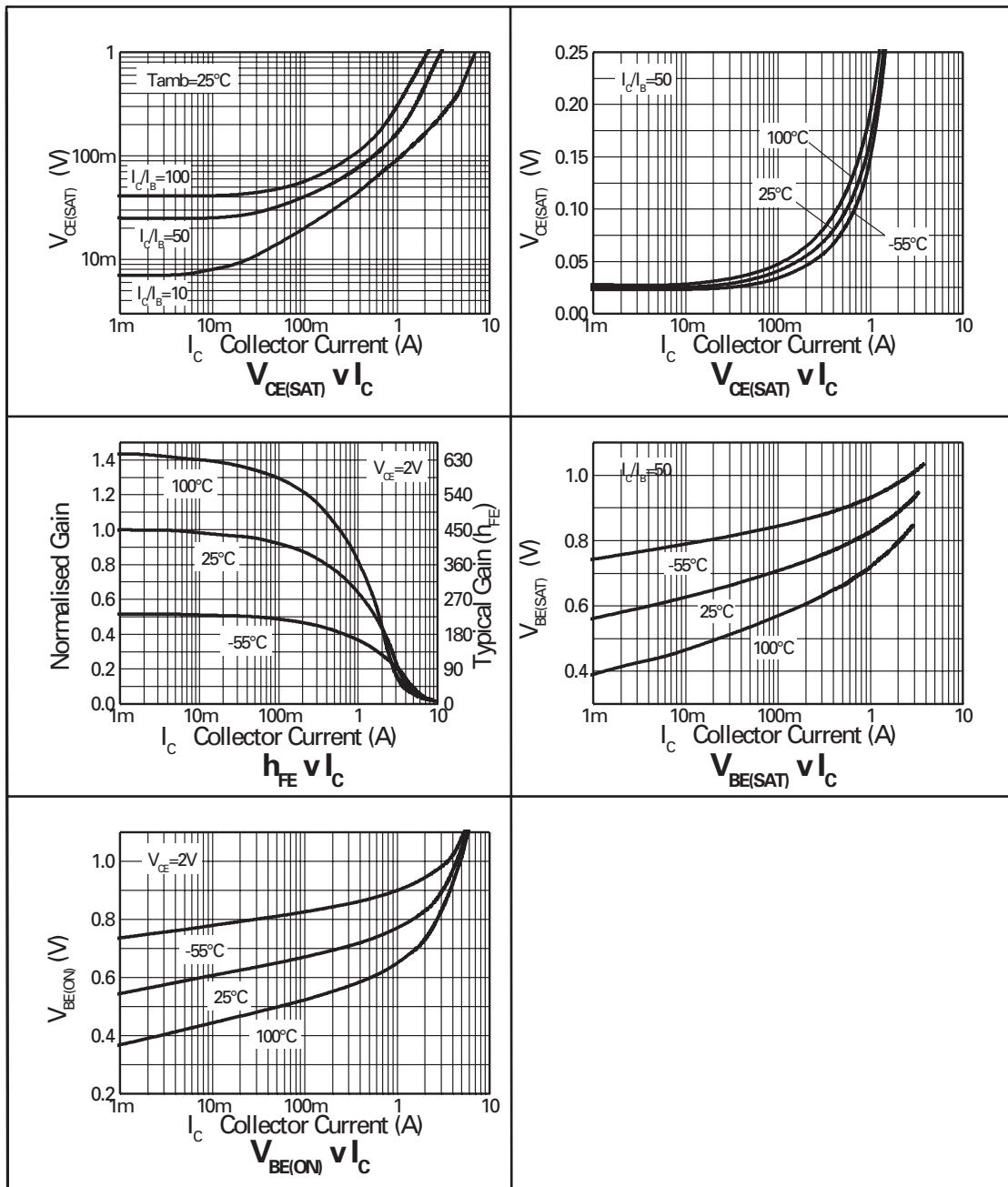
ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^\circ C$ unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.	
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-25	-35		V	$I_C=-100\mu A$	
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-20	-25		V	$I_C=-10mA^*$	
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-7.5	8.5		V	$I_E=-100\mu A$	
Collector Cut-Off Current	I_{CBO}			-25	nA	$V_{CB}=-20V$	
Emitter Cut-Off Current	I_{EBO}			-25	nA	$V_{EB}=-6V$	
Collector Emitter Cut-Off Current	I_{CES}			-25	nA	$V_{CES}=-16V$	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$			-19 -170 -190 -240 -225	mV -220 -250 -350 -300	$I_C=-0.1A, I_B=-10mA^*$ $I_C=-1A, I_B=-20mA^*$ $I_C=-1.5A, I_B=-50mA^*$ $I_C=-2.5A, I_B=-150mA^*$ $I_C=-3.5A, I_B=-350mA^*$	
Base-Emitter Saturation Voltage	$V_{BE(sat)}$			-1.10	-1.075	V	$I_C=-3.5A, I_B=350mA^*$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$			-0.87	-0.95	V	$I_C=-3.5A, V_{CE}=-2V^*$
Static Forward Current Transfer Ratio	h_{FE}	300 300 150 15	475 450 230 30				$I_C=10mA, V_{CE}=-2V^*$ $I_C=-0.1A, V_{CE}=-2V^*$ $I_C=-2A, V_{CE}=-2V^*$ $I_C=-6A, V_{CE}=-2V^*$
Transition Frequency	f_T	150	180		MHz	$I_C=-50mA, V_{CE}=-10V$ $f=100MHz$	
Output Capacitance	C_{obo}			21	30	pF	$V_{CB}=10V, f=1MHz$
Turn-On Time	$t_{(on)}$			40	ns		$V_{CC}=-10V, I_C=1A$
Turn-Off Time	$t_{(off)}$			670	ns		$I_{B1}=I_{B2}=20mA$

*Measured under pulsed conditions. Pulse width=300 μs . Duty cycle $\leq 2\%$

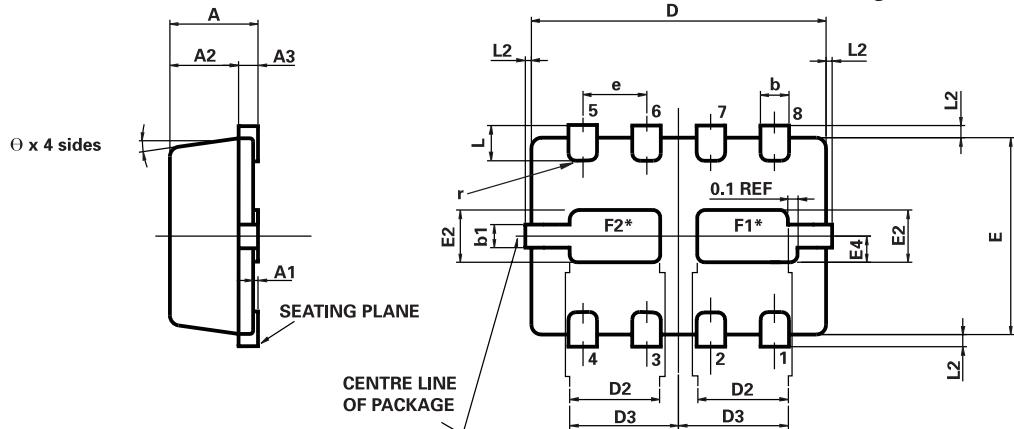
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TYPICAL CHARACTERISTICS



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MLP832 PACKAGE OUTLINE (3mm x 2mm Micro Leaded Package)



*Exposed Flags. Solder connection to improve thermal dissipation is optional.
F1 at collector 1 potential
F2 at collector 2 potential

CONTROLLING DIMENSIONS IN MILLIMETRES
APPROX. CONVERTED DIMENSIONS IN INCHES

MLP832 PACKAGE DIMENSIONS

DIM	MILLIMETRES		INCHES		DIM	MILLIMETRES		INCHES	
	MIN.	MAX.	MIN.	MAX.		MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039	e	0.65	REF	0.0256	BSC
A1	0.00	0.05	0.00	0.002	E	2.00	BSC	0.0787	BSC
A2	0.65	0.75	0.0255	0.0295	E2	0.43	0.63	0.017	0.0249
A3	0.15	0.25	0.006	0.0098	E4	0.16	0.36	0.006	0.014
b	0.24	0.34	0.009	0.013	L	0.20	0.45	0.0078	0.0157
b1	0.17	0.30	0.0066	0.0118	L2	—	0.125	0.00	0.005
D	3.00 BSC		0.118 BSC		r	0.075 BSC		0.0029 BSC	
D2	0.82	1.02	0.032	0.040	Θ	0°	12°	0°	12°
D3	1.01	1.21	0.0397	0.0476					

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Europe	Americas	Asia Pacific	
Zetex plc Fields New Road Chadderton Oldham, OL9 8NP United Kingdom Telephone (44) 161 622 4422 Fax: (44) 161 622 4420 uksales@zetex.com	Zetex GmbH Streiffeldstraße 19 D-81673 München Germany Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Zetex Inc 700 Veterans Memorial Hwy Hauppauge, NY11788 USA Telephone: (631) 360 2222 Fax: (631) 360 8222 usa.sales@zetex.com	Zetex (Asia) Ltd 3701-04 Metroplaza, Tower 1 Hing Fong Road Kwai Fong Hong Kong Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com

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